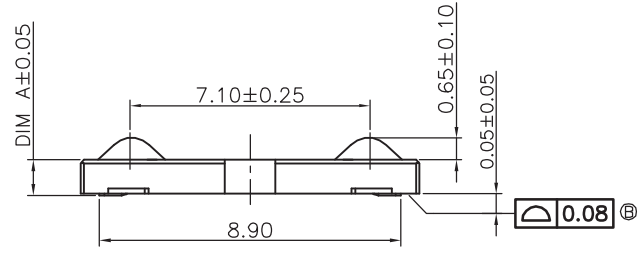
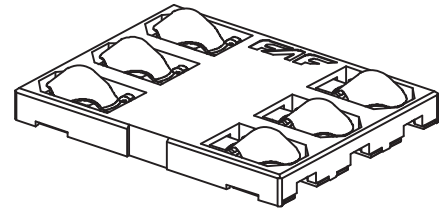
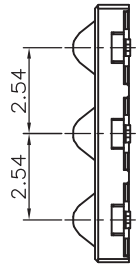
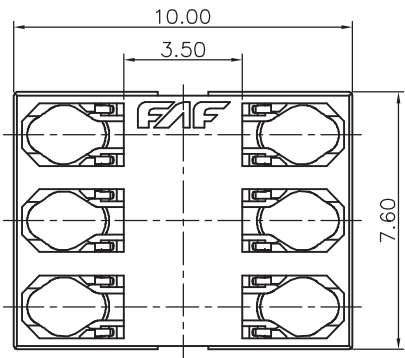
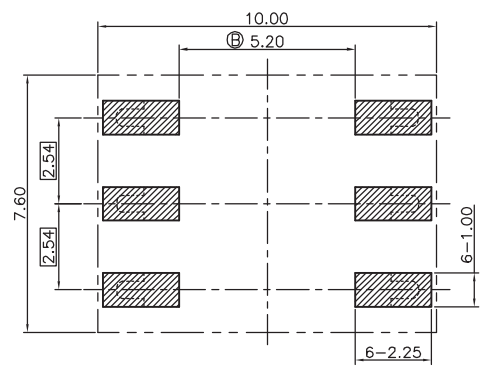
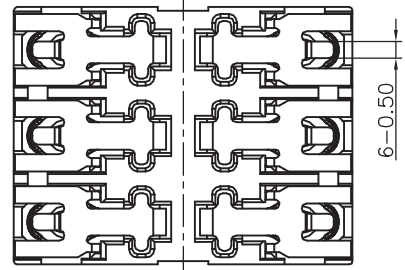


A3

REV	ECN NO	DESCRIPTION	DATE	APPD
A	ECN1210014	NEW RELEASE	2012.10.22	BILL
B		CHANGE DIMENSION	2012.11.10	BILL



- NOTES:
- MATERIAL:
    - HOUSING: HIGH TEMP. PLASTIC,UL94-V0
    - CONTACT: COPPER ALLOY
  - FINISH:
    - CONTACT: CONTACT AREA: Au PLATED OVER Ni PLATED OVER ALL SOLDER AREA: GOLD FLASH
  - ELECTRICAL CHARACTERISTICS:
    - CONTACT CURRENT RATING: 1.0A MAX.
    - CONTACT RESISTANCE: 50 mOHMS MAX.
    - INSULATION RESISTANCE: 1000 MOHMS MIN.
  - MECHANICAL CHARACTERISTICS:
    - NORMAL FORCE: 50gf MIN./PIN
    - DURABILITY : 5000 CYCLES
  - ENVIRONMENT CHARACTERISTICS:
    - OPERATING TEMPERATURE: -25°C~85°C
    - STORAGE TEMPERATURE: -40°C~85°C
  - RECOMMENDED IR REFLOW PROCESS PEAK TEMPERATURE: 260°C MAX, TIME 10s
  - ALL SMT CONTACTS AND PADS CO-PLANARITY: 0.10mm MAX



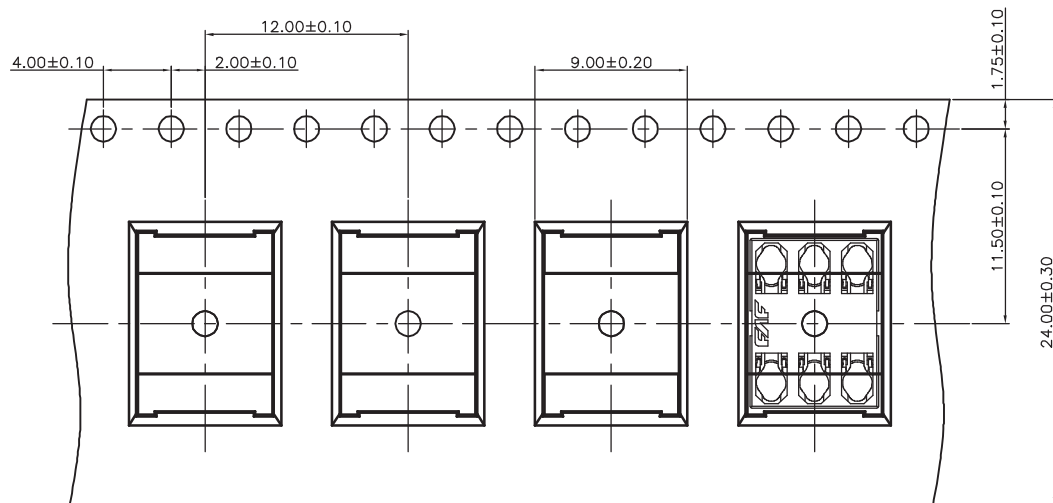
RECOMMENDED PCB LAYOUT  
TOLERANCES ±0.05

1.029A1-006-5R0	1.20
1.029A0-006-5R0	1.05
PART NO.	DIM A

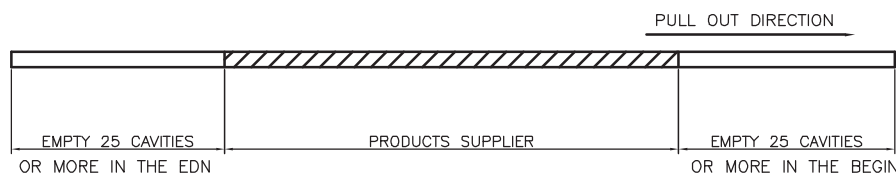
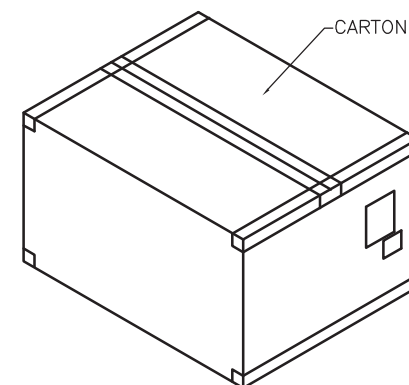
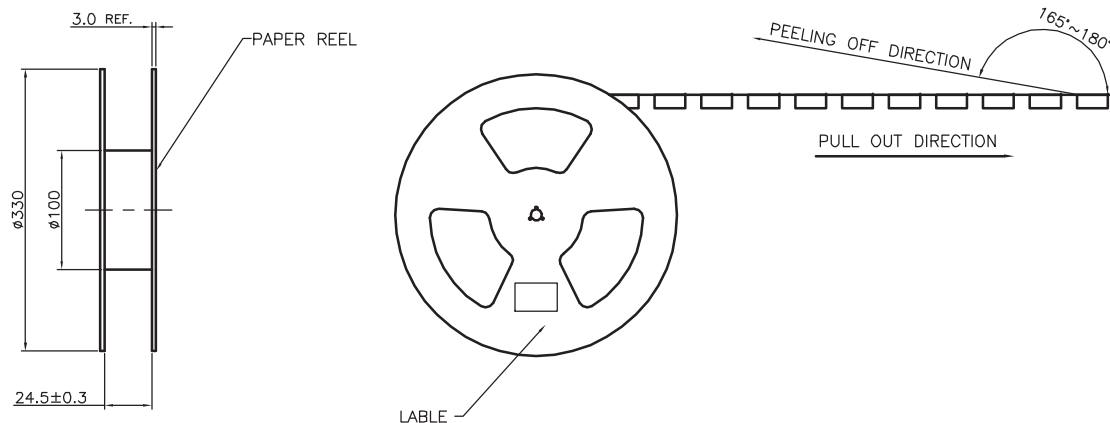
EXTEND USE		TITLE	
SIM CARD CONN.		LOW PROFILE SIM CARD CUSTOMER DRAWING	
UNIT mm		DWG NO C-1.029A0	
GENERAL TOLERANCE		APPD BILL ZHENG 2012.11.10	
DIMENSION	ANGLES	P/N: SEE TABLE	
.0 ±0.30	.0 ±3°	SHEET 1/2	
.0 ±0.25	.0 ±2°	SCALE 1:1	
.00 ±0.20	.00 ±1°	REV B	
.000 ±0.10			
MATERIAL		DRN BELLY ZHANG 2012.11.10	
QTY			
FINISHED			

A3

REV	ECN NO	DESCRIPTION	DATE	APPD
SEE SHEET 1/2				



- Notes:
- MATERIAL:  
CARRIER TAPE: PS.  
COVER TAPE: PE,PET,PEF
  - Q'TY: 2000PCS/REEL, 6000PCS/CARTON
  - PEELING FORCE: 10gf~130gf.



EXTEND USE		TITLE	
SIM CARD CONN.	UNIT mm	LOW PROFILE SIM CARD CUSTOMER DRAWING	
<b>GENERAL TOLERANCE</b>	<b>MATERIAL</b>	APPD BILL ZHENG 2012.11.10	P/N: SEE TABLE
DIMENSION .0 ±0.30 .0 ±0.25 .00 ±0.20 .000 ±0.10	ANGLES ° ±3' ° ±2' ° ±1'	QTY CHD ANDREW ZHANG 2012.11.10	SHEET 2/2
	<b>FINISHED</b>	DRN BELLY ZHANG 2012.11.10	SCALE 1:1
			REV B